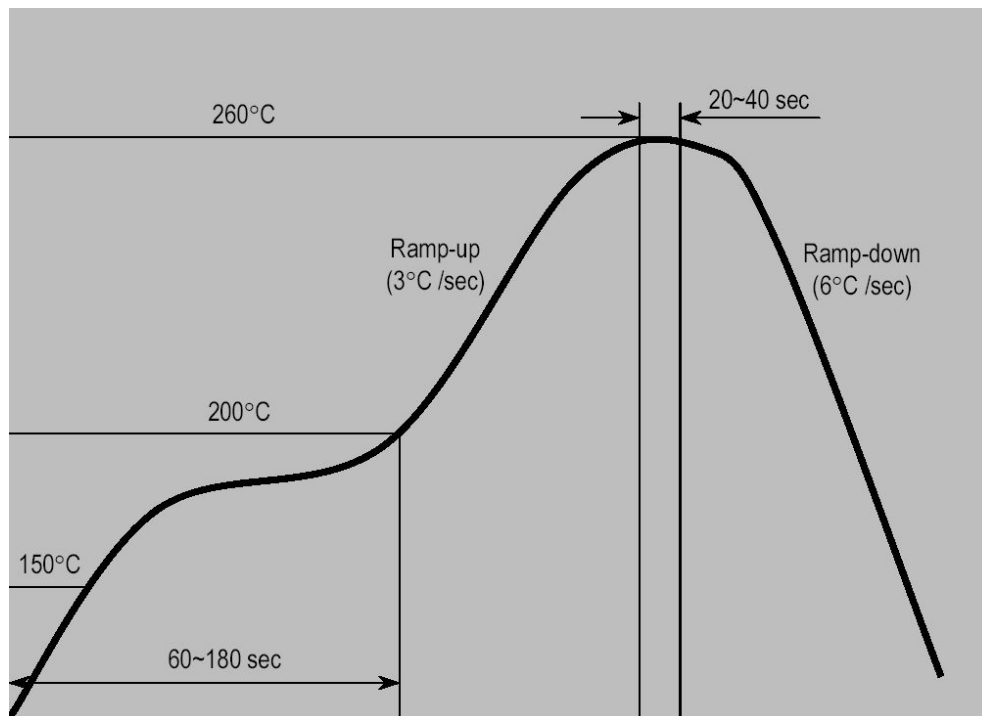


## Recommended Reflow Profile

Applicable Products	All ASB's Plastic Encapsulated Packages – SOT89, SOT363, SOIC8, DFN6
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All ASB's plastic encapsulated packages are lead-free finished by pure matte tin (Sn). This pure matte Sn provides a stable plating for both of SnPb alloy solder process and Pb-free alloy solder process. The recommended reflow profile investigated by ASB for our plastic encapsulated packages is schematized below.



Note: The ramp rate means that only a ramp rate slower than that indicated as 3°C/sec for ramp up and 6°C/sec for ramp down is allowed. The duration time 20~40 sec at 260°C should be kept.